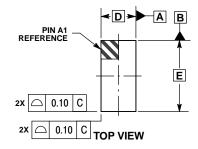
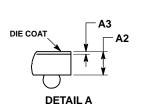
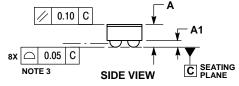


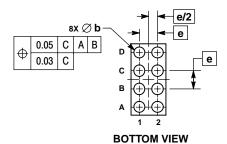
WLCSP8, 1.57x0.77 CASE 499BQ **ISSUE A**

DATE 01 SEP 2015









NOTES:

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS		
DIM	MIN	MAX	
Α		0.50	
A1	0.13	0.17	
A2	0.30 REF		
A3	0.025 BSC		
b	0.21	0.25	
D	0.77 BSC		
E	1.57 BSC		
е	0.40 BSC		

GENERIC MARKING DIAGRAM*



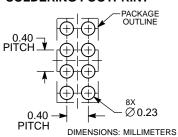
XX = Specific Device Code

YY = Year

WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PAGE 2 OF 2

ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION. REQ. BY J. BASS.	13 APR 2011
Α	ADDED DIE COAT INFORMATION, DETAIL A AND DIMENSIONS A2 & A3. REQ. BY J. BASS.	01 SEP 2015

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